

MOC3061M, MOC3062M, MOC3063M, MOC3162M, MOC3163M 6-Pin DIP Zero-Cross Phototriac Driver Optocoupler (600 Volt Peak)

Features

- Simplifies logic control of 115/240 VAC power
- Zero voltage crossing
- dv/dt of 1000V/ μ s guaranteed (MOC316X-M),
– 600V/ μ s guaranteed (MOC306X-M)
- VDE recognized (File # 94766)
– ordering option V (e.g., MOC3063V-M)
- Underwriters Laboratories (UL) recognized
(File #E90700, volume 2)

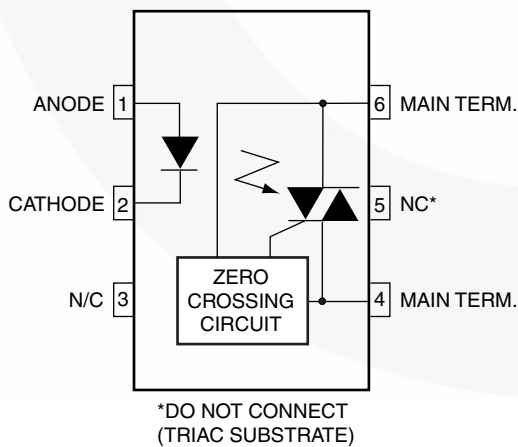
Applications

- Solenoid/valve controls
- Static power switches
- Temperature controls
- AC motor starters
- Lighting controls
- AC motor drives
- E.M. contactors
- Solid state relays

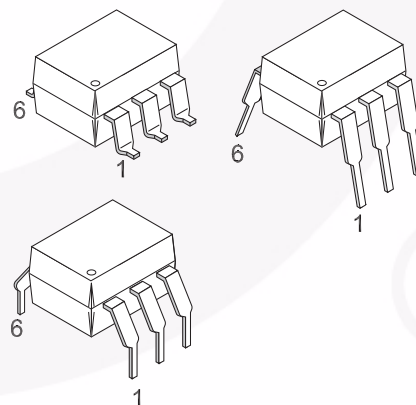
Description

The MOC306XM and MOC316XM devices consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon detector performing the function of a zero voltage crossing bilateral triac driver. They are designed for use with a triac in the interface of logic systems to equipment powered from 115/240 VAC lines, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances, etc.

Schematic



Package Outlines



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Device	Value	Units
TOTAL DEVICE				
T_{STG}	Storage Temperature	All	-40 to +150	$^\circ\text{C}$
T_{OPR}	Operating Temperature	All	-40 to +85	$^\circ\text{C}$
T_{SOL}	Lead Solder Temperature	All	260 for 10 sec	$^\circ\text{C}$
T_J	Junction Temperature Range	All	-40 to +100	$^\circ\text{C}$
V_{ISO}	Isolation Surge Voltage ⁽¹⁾ (peak AC voltage, 60Hz, 1 sec. duration)	All	7500	Vac(pk)
P_D	Total Device Power Dissipation @ 25 $^\circ\text{C}$ Ambient Derate above 25 $^\circ\text{C}$	All	250	mW
			2.94	mW/ $^\circ\text{C}$
EMITTER				
I_F	Continuous Forward Current	All	60	mA
V_R	Reverse Voltage	All	6	V
P_D	Total Power Dissipation @ 25 $^\circ\text{C}$ Ambient Derate above 25 $^\circ\text{C}$	All	120	mW
			1.41	mW/ $^\circ\text{C}$
DETECTOR				
V_{DRM}	Off-State Output Terminal Voltage	All	600	V
I_{TSM}	Peak Repetitive Surge Current (PW = 100 μs , 120pps)	All	1	A
P_D	Total Power Dissipation @ 25 $^\circ\text{C}$ Ambient Derate above 25 $^\circ\text{C}$	All	150	mW
			1.76	mW/ $^\circ\text{C}$

Note:

1. Isolation surge voltage, V_{ISO} , is an internal device dielectric breakdown rating. For this test, Pins 1 and 2 are common, and Pins 4, 5 and 6 are common.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise specified)**Individual Component Characteristics**

Symbol	Parameters	Test Conditions	Device	Min.	Typ.*	Max.	Units
EMITTER							
V_F	Input Forward Voltage	$I_F = 30\text{mA}$	All		1.3	1.5	V
I_R	Reverse Leakage Current	$V_R = 6\text{V}$	All		0.005	100	μA
DETECTOR							
I_{DRM1}	Peak Blocking Current, Either Direction	$V_{\text{DRM}} = 600\text{V}$, $I_F = 0^{(2)}$	MOC316XM		10	100	nA
			MOC306XM		10	500	
dv/dt	Critical Rate of Rise of Off-State Voltage	$I_F = 0$ (Figure 9) ⁽³⁾	MOC306XM	600	1500		V/ μs
			MOC316XM	1000			

Transfer Characteristics

Symbol	DC Characteristics	Test Conditions	Device	Min.	Typ.*	Max.	Units
I_{FT}	LED Trigger Current (rated I_{FT})	Main Terminal Voltage = $3\text{V}^{(3)}$	MOC3061M			15	mA
			MOC3062M/ MOC3162M			10	
			MOC3063M/ MOC3163M			5	
V_{TM}	Peak On-State Voltage, Either Direction	$I_{\text{TM}} = 100\text{mA}$ peak, $I_F = \text{rated } I_{\text{FT}}$	All		1.8	3	V
I_{H}	Holding Current, Either Direction		All		500		μA

Zero Crossing Characteristics

Symbol	Characteristics	Test Conditions	Device	Min.	Typ.*	Max.	Units
V_{INH}	Inhibit Voltage (MT1-MT2 voltage above which device will not trigger)	$I_F = \text{Rated } I_{\text{FT}}$	MOC3061M/2M/3M		12	20	V
			MOC3162M/3M		12	15	
I_{DRM2}	Leakage in Inhibited State	$I_F = \text{Rated } I_{\text{FT}}$, $V_{\text{DRM}} = 600\text{V}$, off state	All			2	mA

Isolation Characteristics

Symbol	Characteristics	Test Conditions	Device	Min.	Typ.*	Max.	Units
V_{ISO}	Isolation Voltage	f = 60 Hz, t = 1 sec	All	7500			V

*Typical values at $T_A = 25^\circ\text{C}$ **Notes:**

- Test voltage must be applied within dv/dt rating.
- All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT} . Therefore, recommended operating I_F lies between max I_{FT} (15mA for MOC3061M, 10mA for MOC3062M & MOC3162M, 5mA for MOC3063M & MOC3163M) and absolute max I_F (60mA).
- This is static dv/dt. See Figure 9 for test circuit. Commutating dv/dt is a function of the load-driving thyristor(s) only.

Safety and Insulation Ratings

As per IEC 60747-5-2, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Typ.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For Rated Main Voltage < 150Vrms		I-IV		
	For Rated Main voltage < 300Vrms		I-IV		
	Climatic Classification		55/100/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V_{PR}	Input to Output Test Voltage, Method b, $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with $t_m = 1$ sec, Partial Discharge < 5pC	1594			V_{peak}
	Input to Output Test Voltage, Method a, $V_{IORM} \times 1.5 = V_{PR}$, Type and Sample Test with $t_m = 60$ sec, Partial Discharge < 5pC	1275			V_{peak}
V_{IORM}	Max. Working Insulation Voltage	850			V_{peak}
V_{IOTM}	Highest Allowable Over Voltage	6000			V_{peak}
	External Creepage	7			mm
	External Clearance	7			mm
	Insulation Thickness	0.5			mm
RIO	Insulation Resistance at T_s , $V_{IO} = 500V$	10^9			Ω

Typical Performance Curves

Figure 1. LED Forward Voltage vs. Forward Current

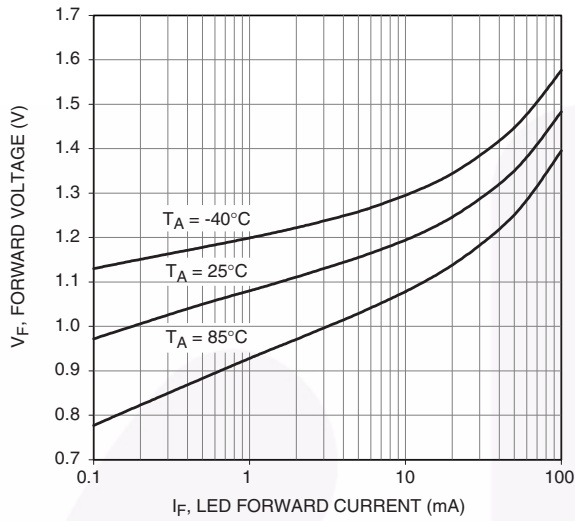


Figure 2. Trigger Current Vs. Temperature

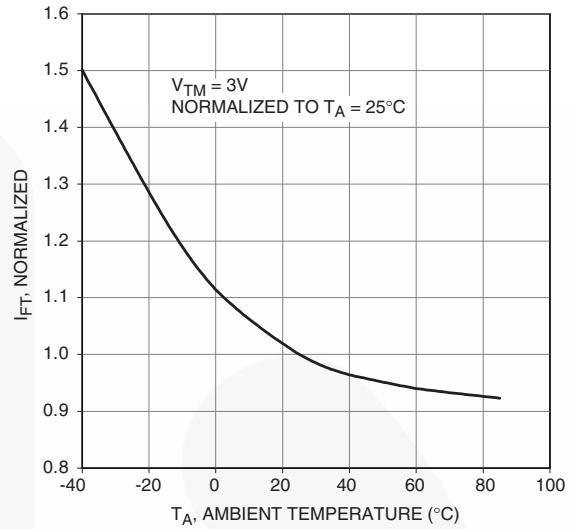


Figure 3. LED Current Required to Trigger vs. LED Pulse Width

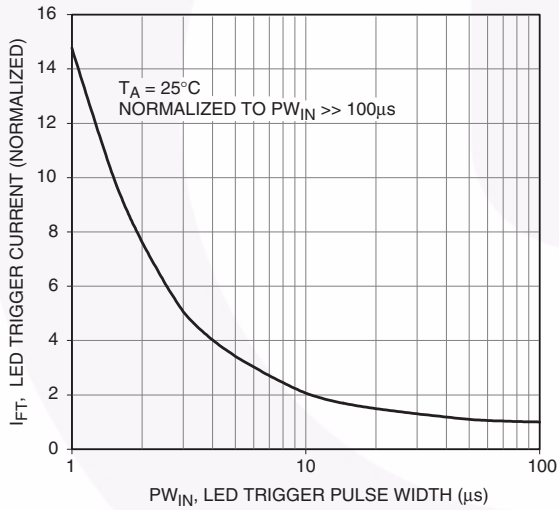
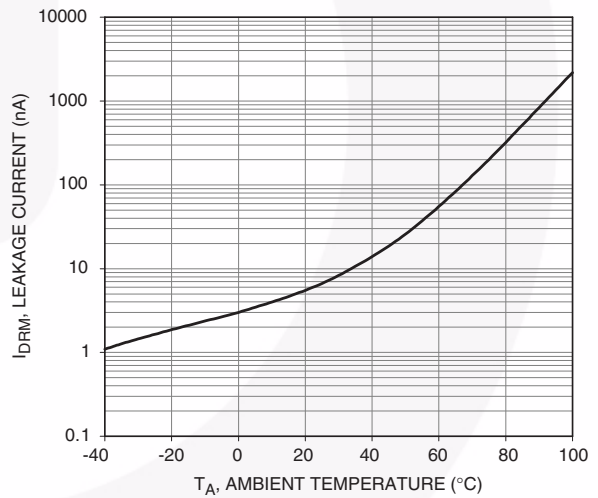


Figure 4. Leakage Current, I_{DRM} vs. Temperature



Typical Performance Curves (Continued)

Figure 5. I_{DRM2} , Leakage in Inhibit State vs. Temperature

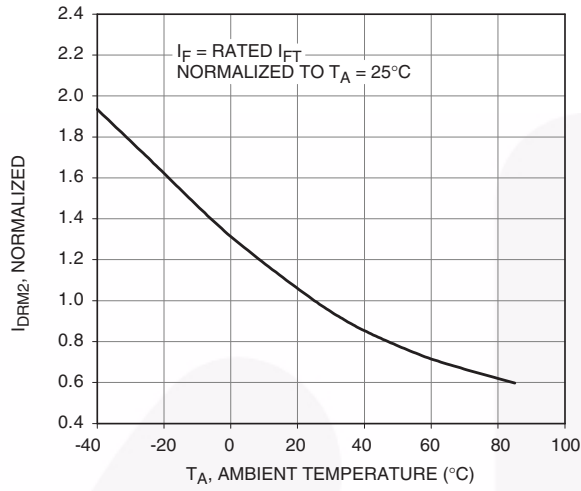


Figure 6. On-State Characteristics

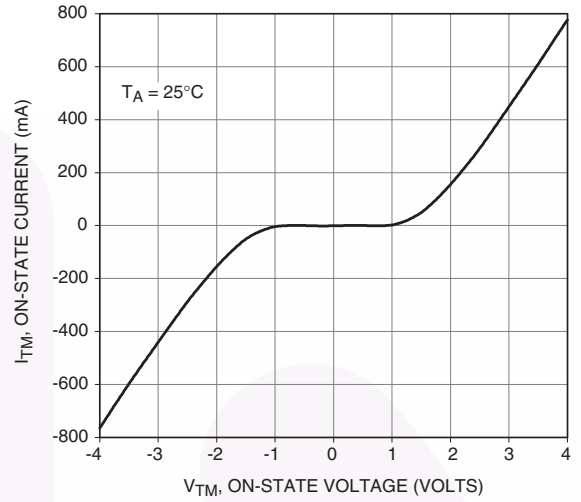


Figure 7. I_H , Holding Current vs. Temperature

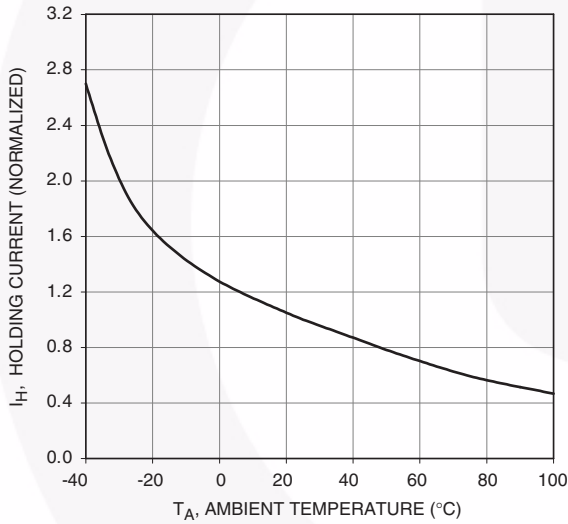
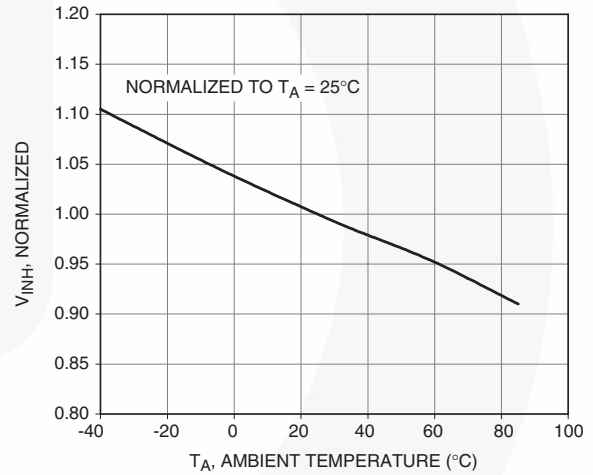
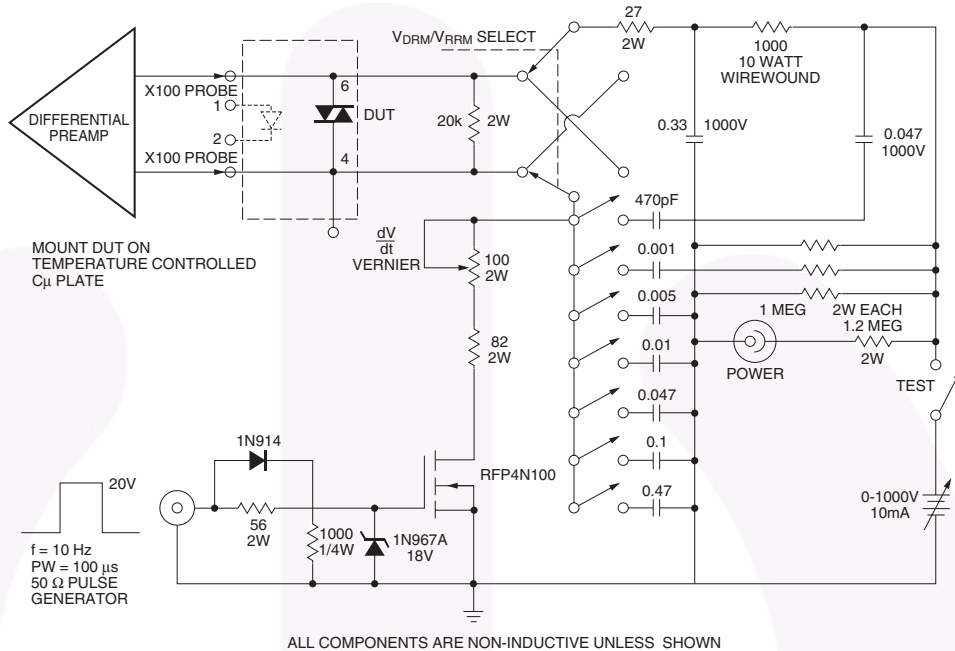


Figure 8. Inhibit Voltage vs. Temperature



1. 100x scope probes are used, to allow high speeds and voltages.
2. The worst-case condition for static dv/dt is established by triggering the D.U.T. with a normal LED input current, then removing the current. The variable vernier resistor combined with various capacitor combinations allows the dv/dt to be gradually increased until the D.U.T. continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the D.U.T. stops triggering. t_{RC} is measured at this point and recorded.



ALL COMPONENTS ARE NON-INDUCTIVE UNLESS SHOWN
Figure 9. Circuit for Static $\frac{dv}{dt}$ Measurement of Power Thyristors

Basic Applications

Typical circuit for use when hot line switching is required. In this circuit the “hot” side of the line is switched and the load connected to the cold or neutral side. The load may be connected to either the neutral or hot line.

R_{in} is calculated so that I_F is equal to the rated I_{FT} of the part, 15mA for the MOC3061M, 10mA for the MOC3062M, or 5mA for the MOC3063M. The 39Ω resistor and 0.01μF capacitor are for snubbing of the triac and is often, but not always, necessary depending upon the particular triac and load used.

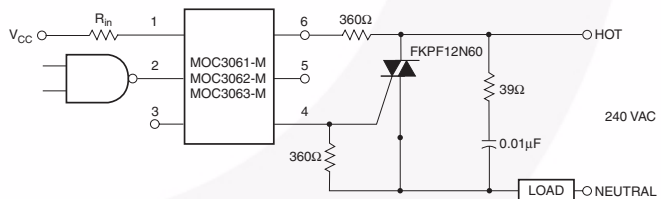


Figure 10. Hot-Line Switching Application Circuit

Suggested method of firing two, back-to-back SCR's with a Fairchild triac driver. Diodes can be 1N4001; resistors, R1 and R2, are optional 330Ω.

Note:

This optoisolator should not be used to drive a load directly. It is intended to be a trigger device only.

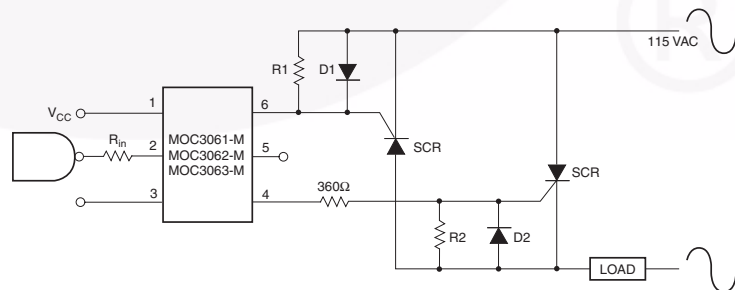


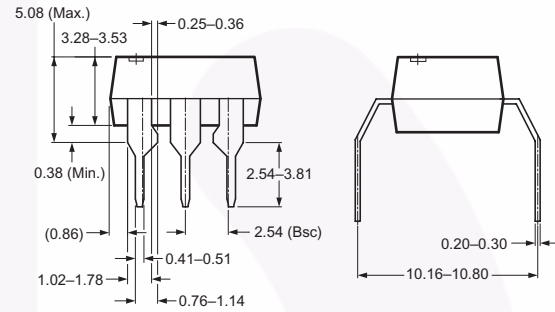
Figure 11. Inverse-Parallel SCR Driver Circuit

Package Dimensions

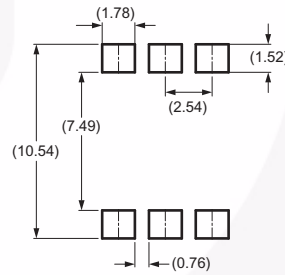
Through Hole



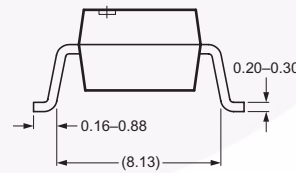
0.4" Lead Spacing



Surface Mount



Recommended Pad Layout



Note:
All dimensions in mm.

Ordering Information

Option	Order Entry Identifier (Example)	Description
No option	MOC3061M	Standard Through Hole Device
S	MOC3061SM	Surface Mount Lead Bend
SR2	MOC3061SR2M	Surface Mount; Tape and Reel
T	MOC3061TM	0.4" Lead Spacing
V	MOC3061VM	VDE 0884
TV	MOC3061TVM	VDE 0884, 0.4" Lead Spacing
SV	MOC3061SVM	VDE 0884, Surface Mount
SR2V	MOC3061SR2VM	VDE 0884, Surface Mount, Tape and Reel

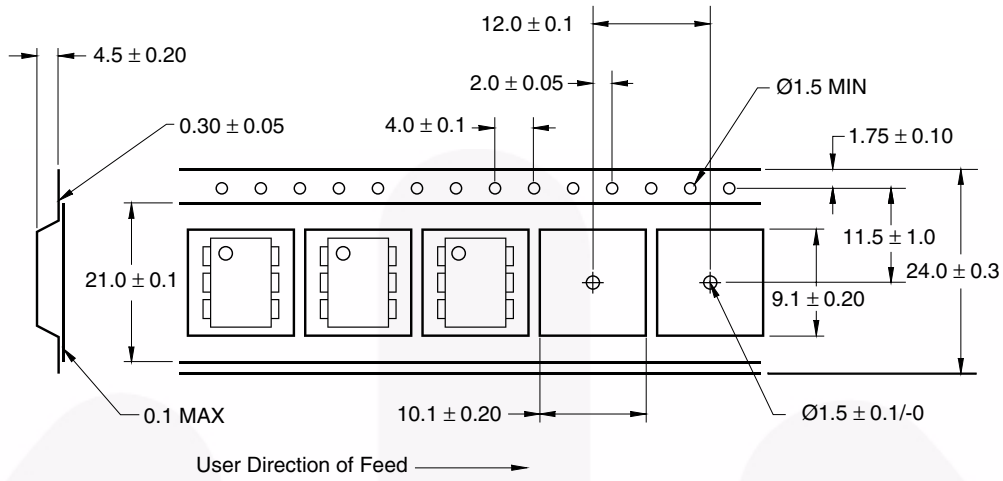
Marking Information



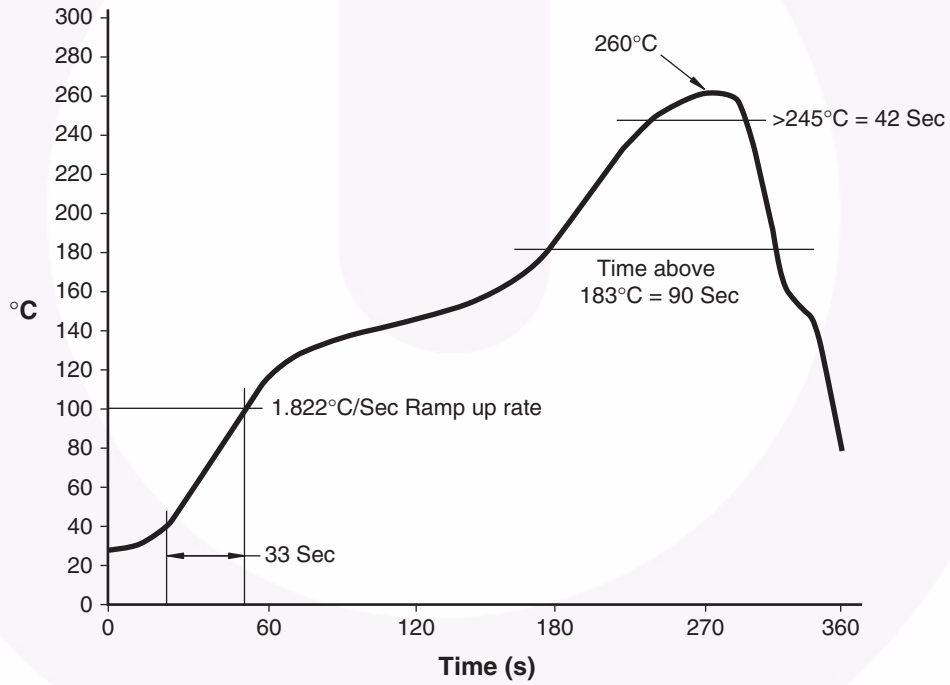
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

*Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.

Carrier Tape Specification



Reflow Profile





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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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